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*Pre Amended
S. Zimmerman*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/921,867

Filed: August 3, 2001

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: June 4, 2002

Group Art Unit: 3729

Examiner:

Docket No.: YOR919930028US6

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Assistant Commissioner for Patents
Washington, D. C. 20231

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2002.

[Signature]
Dr. Daniel P. Morris, Esq.
Reg. No. 32,053

FORTH PRELIMINARY AMENDMENT

IN THE CLAIMS

*37
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1.120*
4 4
Added claims ~~145-195~~

144
~~145~~ (Added) A semiconductor device comprising:

a silicon body having a plurality of contact locations;

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01 FC:103

918.00 CH

02 FC:102

1008.00 CH

Serial No. 09/921,867

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